

PS9309L, PS9309L2

Data Sheet

R08DS0047EJ0100

Rev.1.00

Mar 28, 2014

LOW IF TOTEM POLE OUTPUT TYPE HIGH CMR, IPM DRIVER, 6-PIN SDIP PHOTOCOUPLER

DESCRIPTION

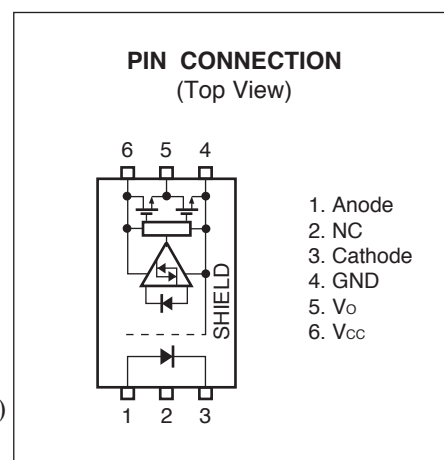
The PS9309L and PS9309L2 are optical coupled high-speed, totem pole output (active high output type) isolators containing a GaAlAs LED on the input side and a photodiode and a signal processing circuit on the output side on one chip.

The PS9309L and PS9309L2 are specified high CMR and pulse width distortion with operating temperature. It is suitable for IPM (Intelligent Power Module) drive.

The PS9309L is lead bending type (Gull-wing) for surface mounting. The PS9309L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

FEATURES

- Totem pole output (Active High Output Type)
- Pulse width distortion ($|t_{PLH} - t_{PHL}| = 80 \text{ ns MAX.}$)
- High common mode transient immunity ($CM_H, CM_L = \pm 15 \text{ kV}/\mu\text{s MIN.}$)
- Half size of 8-pin DIP
- <R> • Long creepage distance (8 mm MIN.: PS9309L2)
- High isolation voltage ($BV = 5\,000 \text{ V r.m.s.}$)
- Embossed tape product : PS9309L-E3, PS9309L2-E3: 2 000 pcs/reel
- Pb-Free product
- Safety standards
 - UL approved: No. E72422
 - CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
- <R> • SEMKO approved (EN 60065, EN 60950)
- <R> • DIN EN 60747-5-5 (VDE 0884-5) approved (Option)

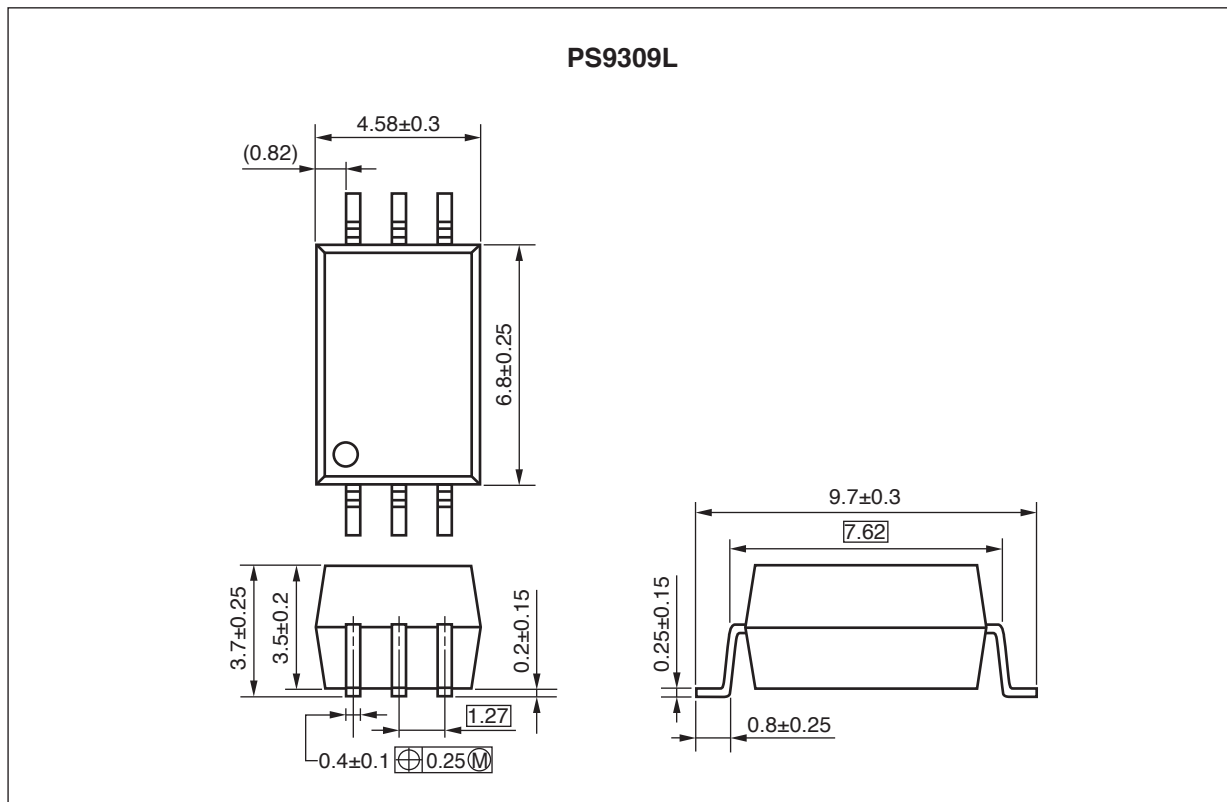
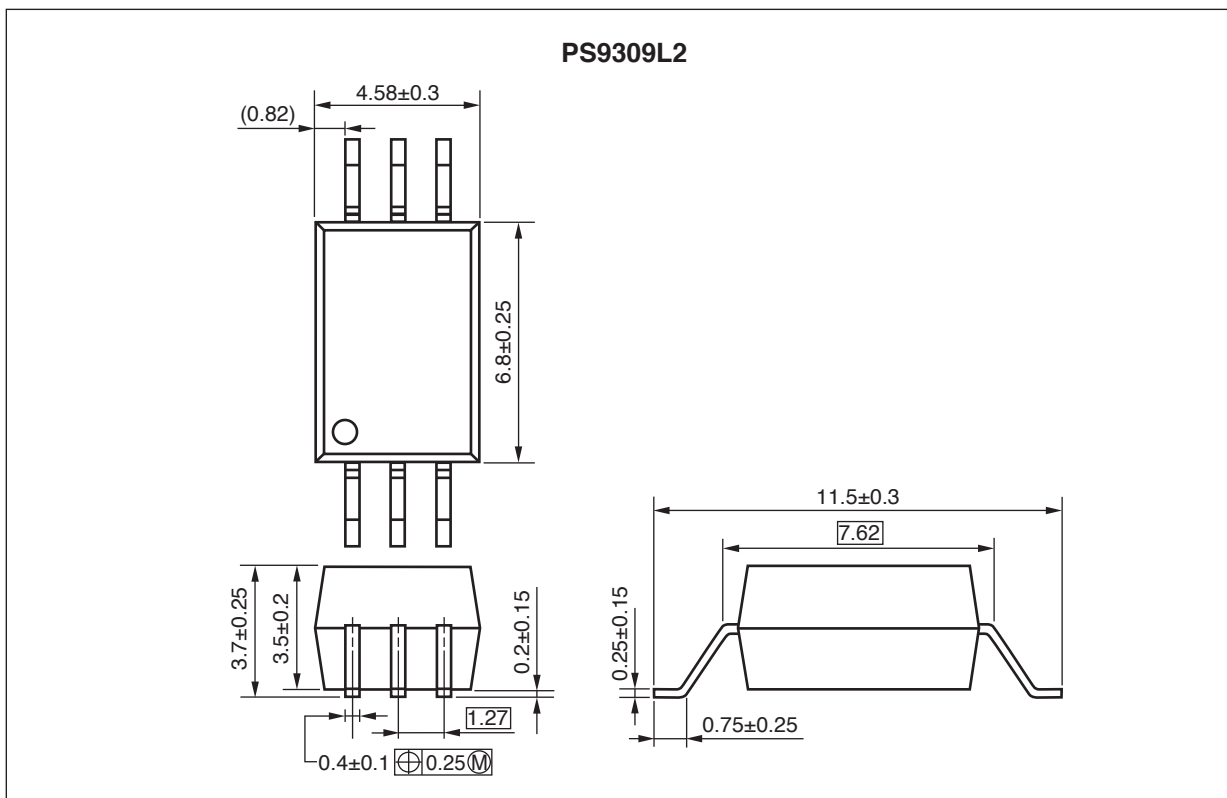


APPLICATIONS

- IPM Driver
- General purpose inverter

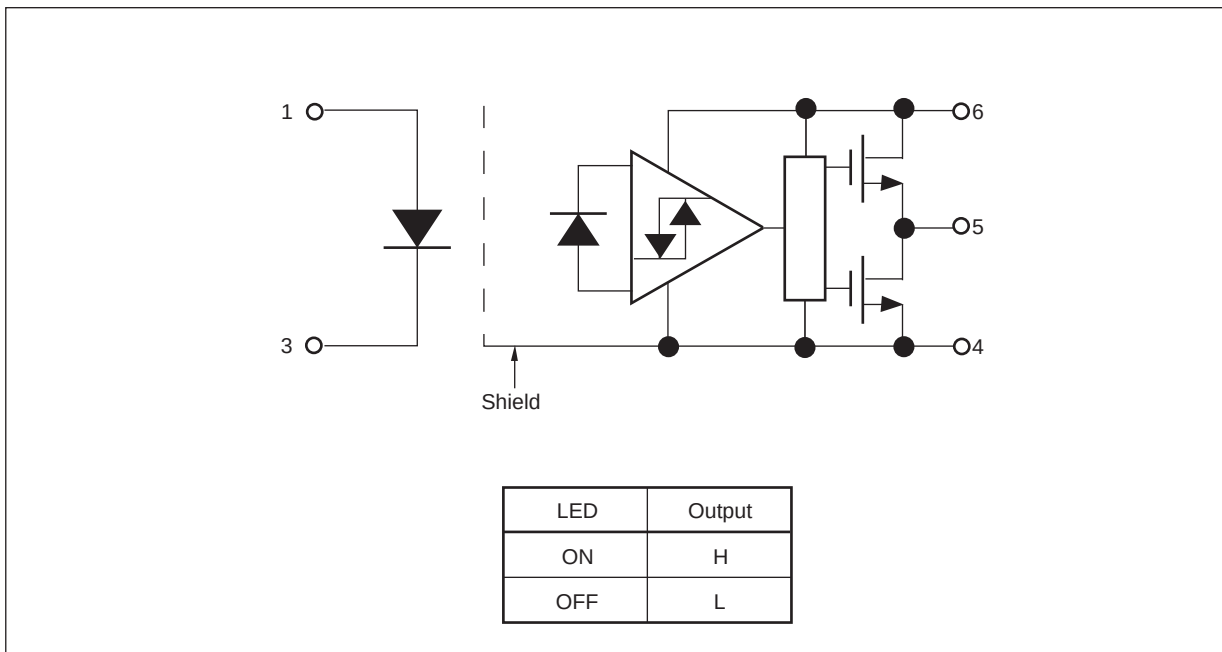
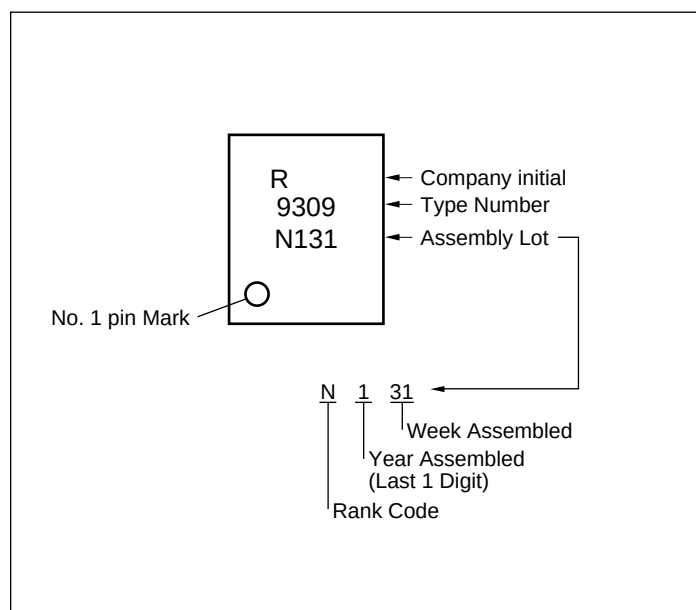
The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (UNIT: mm)**Lead Bending Type (Gull-wing) For Surface Mount****Lead Bending Type (Gull-wing) For Long Creepage Distance (Surface Mount)**

PHOTOCOUPLER CONSTRUCTION

Parameter	PS9309L	PS9309L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

BLOCK DIAGRAM**MARKING EXAMPLE**

<R> **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS9309L	PS9309L-AX	Pb-Free (Ni/Pd/Au)	20 pcs (Tape 20 pcs cut)	Standard products (UL, CSA, SEMKO approved)	PS9309L
PS9309L-E3	PS9309L-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9309L2	PS9309L2-AX		20 pcs (Tape 20 pcs cut)		PS9309L2
PS9309L2-E3	PS9309L2-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9309L-V	PS9309L-V-AX		20 pcs (Tape 20 pcs cut)	UL, CSA, SEMKO DIN EN 60747-5-5 (VDE 0884-5) approved	PS9309L
PS9309L-V-E3	PS9309L-V-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9309L2-V	PS9309L2-V-AX		20 pcs (Tape 20 pcs cut)		PS9309L2
PS9309L2-V-E3	PS9309L2-V-E3-AX		Embossed Tape 2 000 pcs/reel		

Note: ^{*1}. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current ^{*1}	I_F	20	mA
	Reverse Voltage	V_R	5	V
Detector	Supply Voltage	V_{CC}	-0.5 to +25	V
	Output Voltage	V_O	-0.5 to +25	V
	Output Current	I_O	25	mA
	Power Dissipation ^{*2}	P_C	210	mW
Isolation Voltage ^{*3}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T_A	-40 to +110	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +125	$^\circ\text{C}$

Notes: *1. Reduced to 0.32 mA/ $^\circ\text{C}$ at $T_A = 70^\circ\text{C}$ or more.

*2. Reduced to 3.75 mW/ $^\circ\text{C}$ at $T_A = 70^\circ\text{C}$ or more

*3. AC voltage for 1 minute at $T_A = 25^\circ\text{C}$, RH = 60% between input and output.

Pins 1-3 shorted together, 4-6 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V_{CC}	4.5	15	20	V
Output Voltage	V_O	0		20	V
Forward Current (ON)	$I_{F(ON)}$	4		10	mA
Forward Voltage (OFF)	$V_{F(OFF)}$	0		0.8	V

ELECTRICAL CHARACTERISTICS

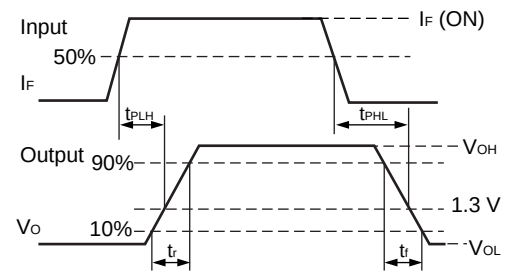
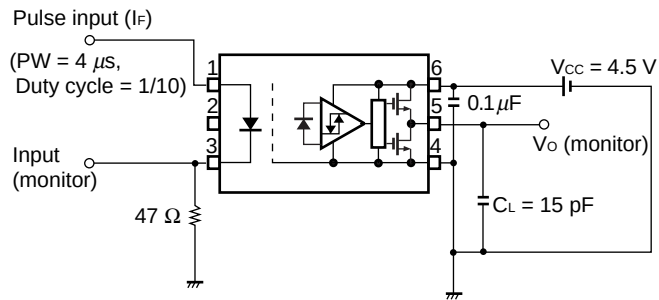
(T_A = -40 to +110°C, V_{CC} = 4.5 to 20 V, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.* ¹	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA, T _A = 25°C	1.3	1.55	1.8	V
	Reverse Current	I _R	V _R = 3 V, T _A = 25°C			10	μA
	Input Capacitance	C _t	V _F = 0 V, f = 1 MHz, T _A = 25°C		30		pF
Detector	High Level Output Voltage	V _{OH}	V _{CC} = 4.5 V, I _O = -2.6 mA, I _F = 4 mA	2.7	3.2		V
			V _{CC} = 20 V, I _O = -2.6 mA, I _F = 4 mA	17.4	18.6		
	Low Level Output Voltage* ²	V _{OL}	I _O = 3.5 mA, I _F = 0 mA		0.25	0.6	V
	High Level Supply Current	I _{CCH}	V _{CC} = 4.5 V, I _F = 4 mA		0.98	3	mA
			V _{CC} = 20 V, I _F = 4 mA		1.32	3	
	Low Level Supply Current	I _{CCL}	V _{CC} = 4.5 V, I _F = 0 mA		1.23	3	mA
			V _{CC} = 20 V, I _F = 0 mA		1.53	3	
	High Level Output Short* ³ Circuit Current	I _{OSH}	V _{CC} = 4.5 V, V _O = GND, I _F = 4 mA	-7	-45		mA
	Low Level Output Short* ³ Circuit Current	I _{OSL}	V _{CC} = V _O = 4.5 V, V _F = 0 V	7	34		mA
Coupled	Threshold Input Current	I _{FLH}	V _{CC} = 4.5 V, V _O > 2.7 V, I _O = -2.6 mA		1.57	3	mA
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC} , RH = 60%, T _A = 25°C	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz, T _A = 25°C		0.6		pF
	Propagation Delay Time (H → L)* ⁴	t _{PHL}	C _L = 15 pF, I _F = 4 → 0 mA, V _{THHL} = 1.3 V		124	200	ns
	Propagation Delay Time (L → H)* ⁴	t _{PLH}	C _L = 15 pF, I _F = 0 → 4 mA, V _{THLH} = 1.3 V		113	200	ns
	Pulse Width Distortion (PWD)	t _{PLH} - t _{PHL}	C _L = 15 pF, I _F = 4 ↔ 0 mA		11	80	ns
	Maximum Propagation Delays (PDD)					80	
	Rise Time (10-90%)* ⁴	t _r	C _L = 15 pF, I _F = 0 → 4 mA		24		ns
	Fall Time (90-10%)* ⁴	t _f	C _L = 15 pF, I _F = 4 → 0 mA		3.2		ns
	Common Mode Transient Immunity at High Level Output* ⁵	CM _H	V _{CC} = 5 V, T _A = 25°C, I _F = 4 mA, V _{CM} = 1.0 kV	15			kV/μs
	Common Mode Transient Immunity at Low Level Output* ⁵	CM _L	V _{CC} = 5 V, T _A = 25°C, I _F = 0 mA, V _{CM} = 1.0 kV	15			kV/μs

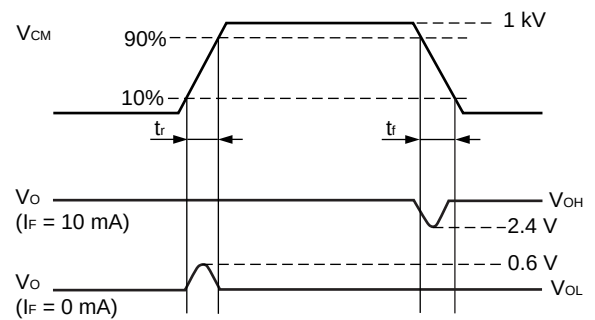
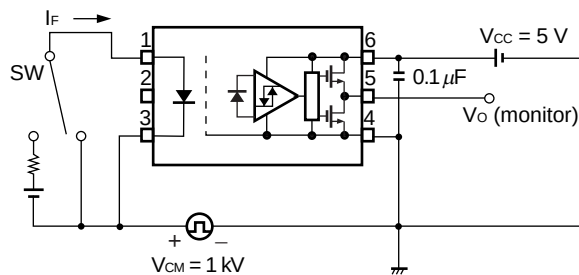
Notes: *1. Typical values at T_A = 25°C

*2. Because V_O of 2.4 V may be output when the LED current is not input and when output supply of V_{CC} = 4.5 V or less, it is important to confirm the characteristics (operation with the power supply on and off) during design, before using this device.

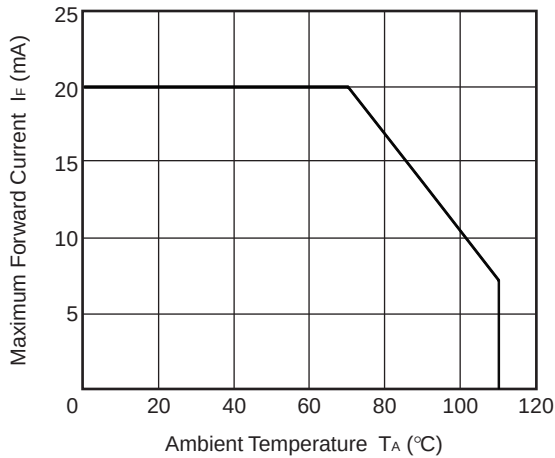
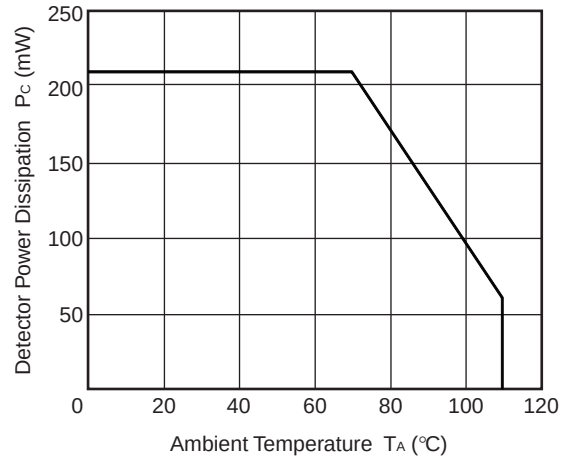
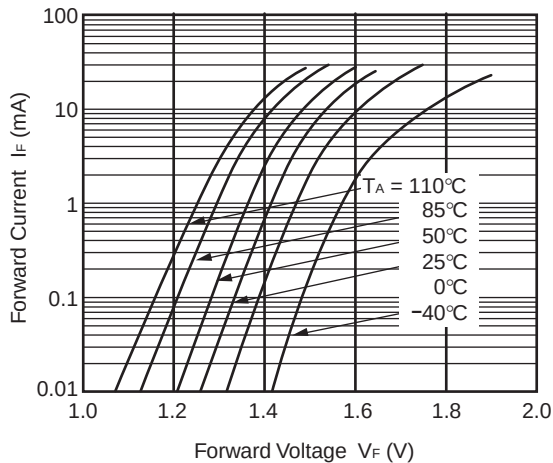
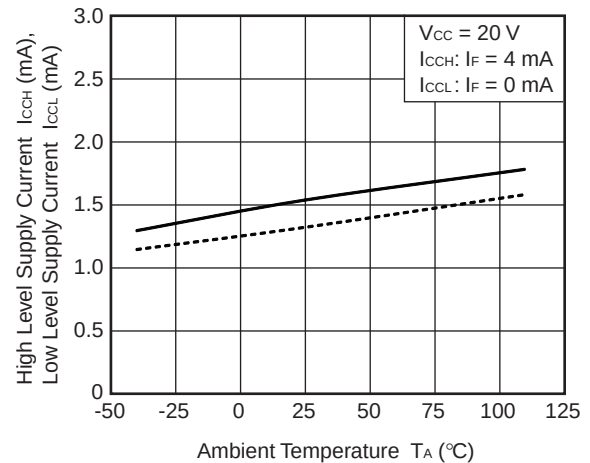
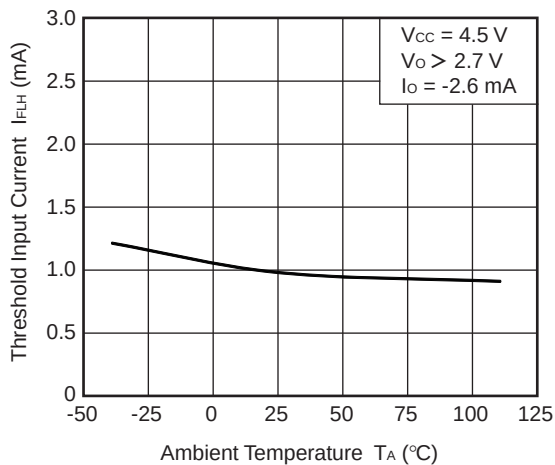
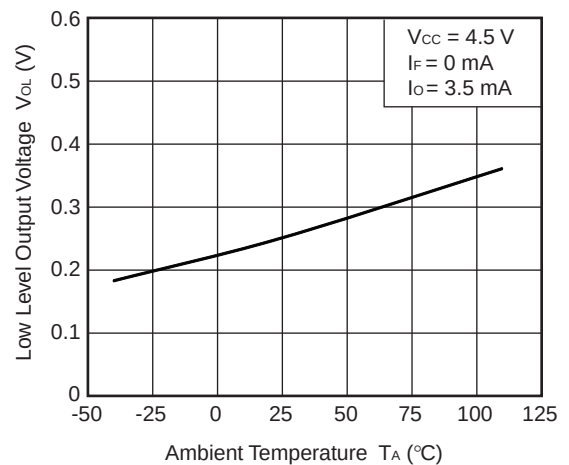
*3. Duration of output short circuit time should not exceed 10 ms.

PS9309L, PS9309L2
***4. Test circuit for propagation delay time**


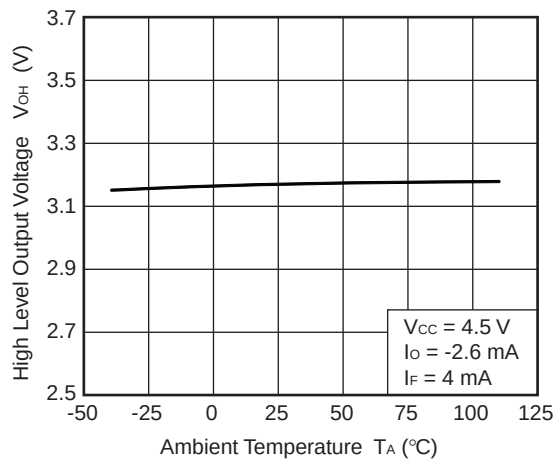
Remark C_L includes probe and stray wiring capacitance.

***5. Test circuit for common mode transient immunity**


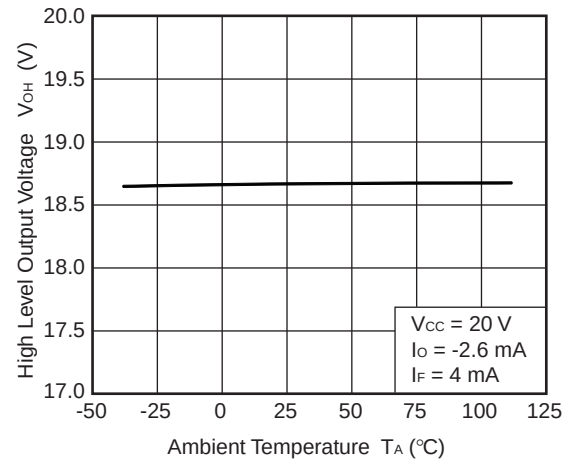
Remark C_L includes probe and stray wiring capacitance.

<R> **TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)****MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE****DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE****FORWARD CURRENT vs. FORWARD VOLTAGE****SUPPLY CURRENT vs. AMBIENT TEMPERATURE****THRESHOLD INPUT CURRENT vs. AMBIENT TEMPERATURE****LOW LEVEL OUTPUT VOLTAGE vs. AMBIENT TEMPERATURE****Remark** The graphs indicate nominal characteristics.

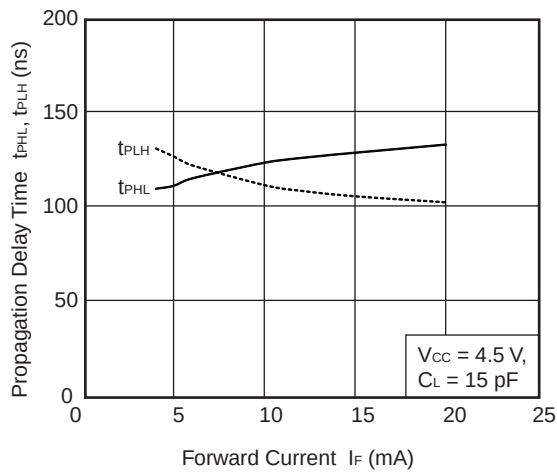
**HIGH LEVEL OUTPUT VOLTAGE
vs. AMBIENT TEMPERATURE**



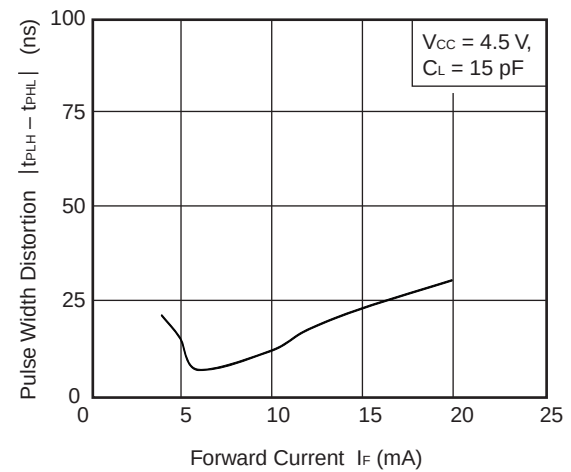
**HIGH LEVEL OUTPUT VOLTAGE
vs. AMBIENT TEMPERATURE**



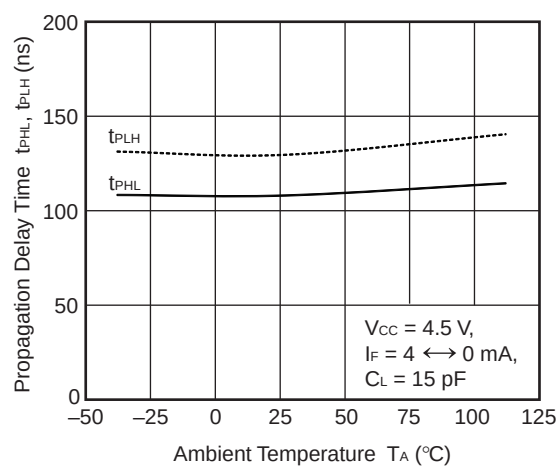
**PROPAGATION DELAY TIME
vs. FORWARD CURRENT**



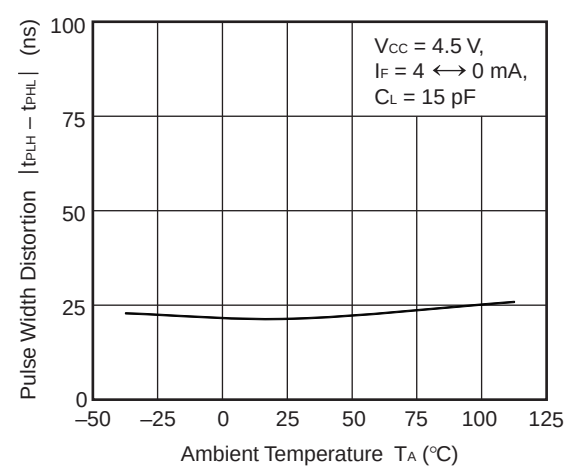
**PULSE WIDTH DISTORTION
vs. FORWARD CURRENT**



**PROPAGATION DELAY TIME
vs. AMBIENT TEMPERATURE**



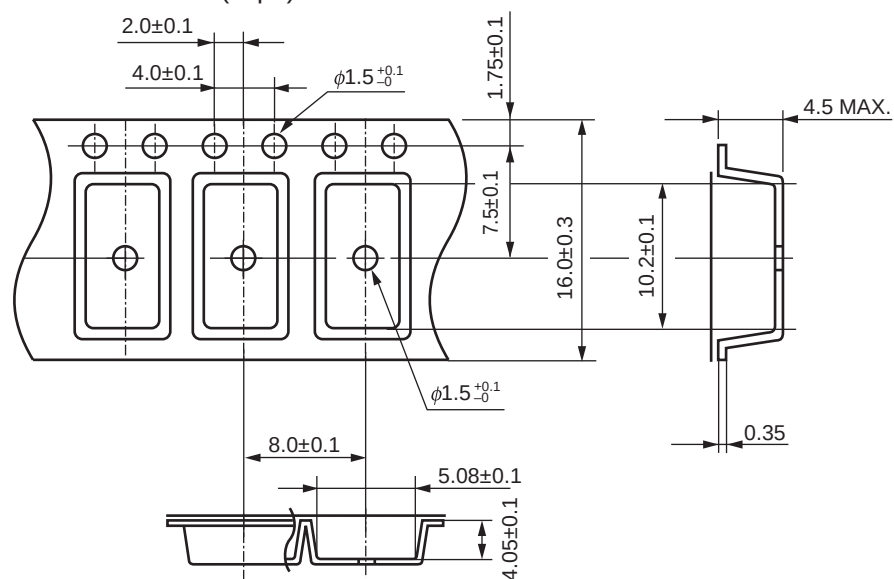
**PULSE WIDTH DISTORTION
vs. AMBIENT TEMPERATURE**



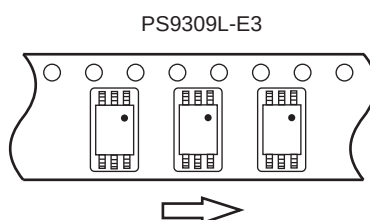
Remark The graphs indicate nominal characteristics.

<R> TAPING SPECIFICATIONS (UNIT: mm)

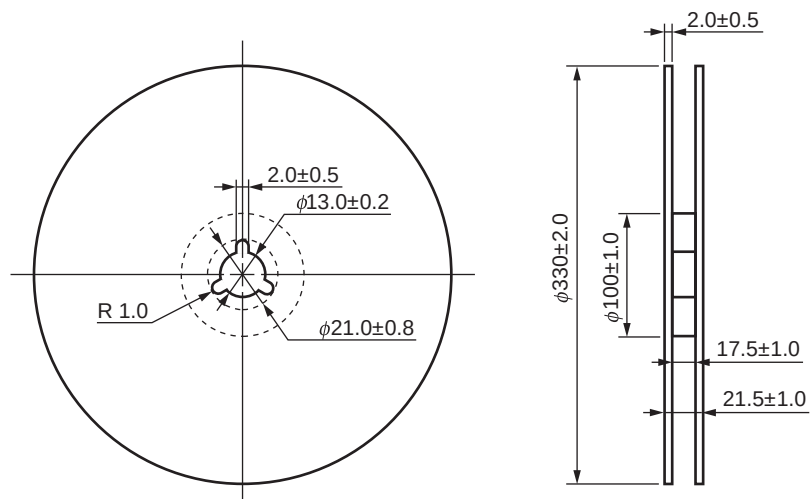
Outline and Dimensions (Tape)



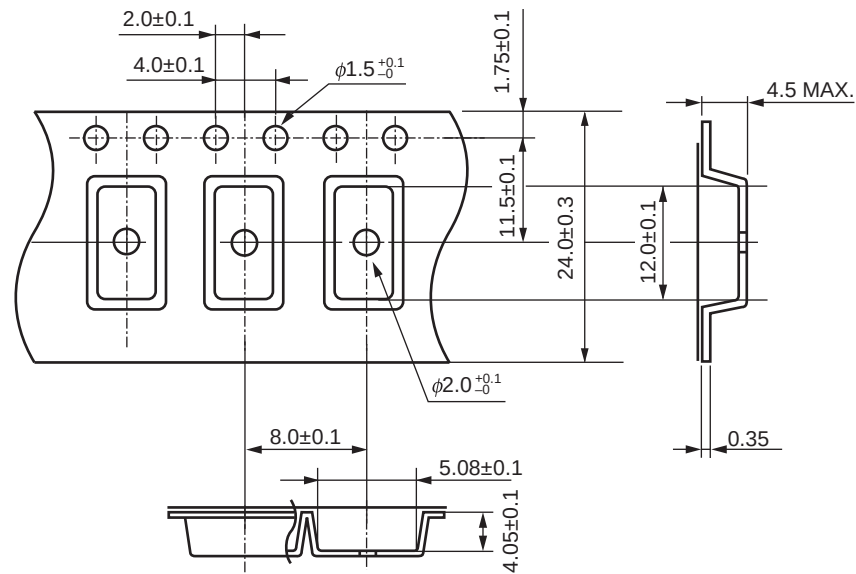
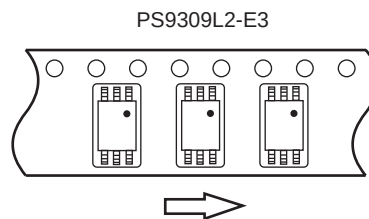
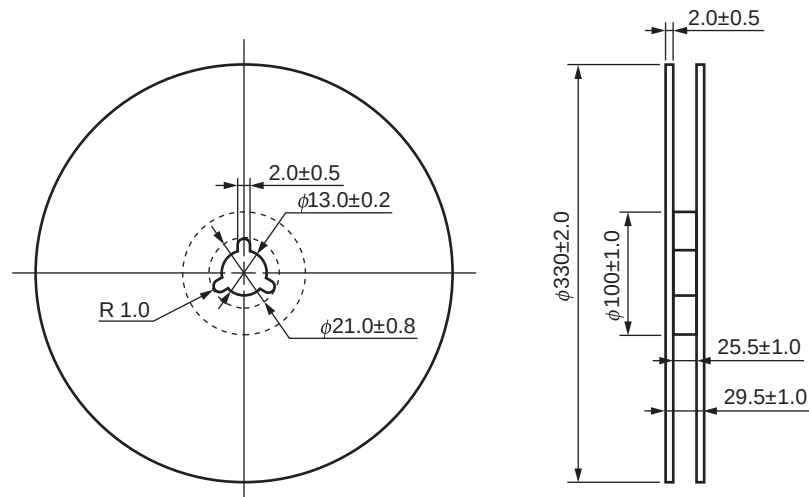
Tape Direction



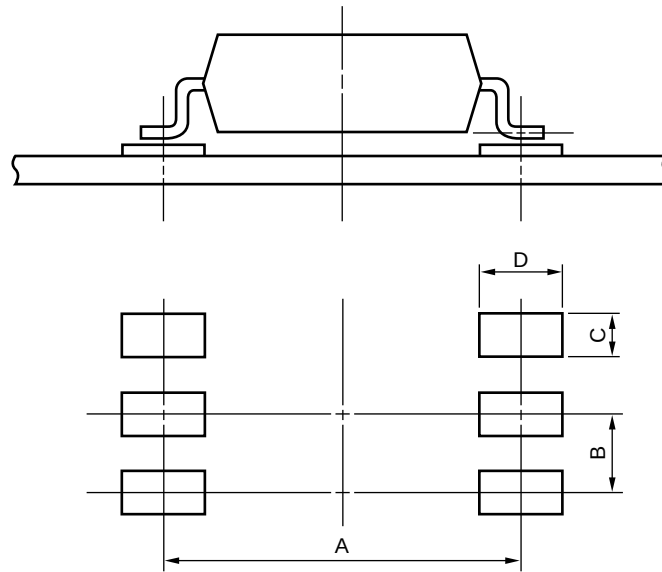
Outline and Dimensions (Reel)



Packing: 2 000 pcs/reel

Outline and Dimensions (Tape)**Tape Direction****Outline and Dimensions (Reel)**

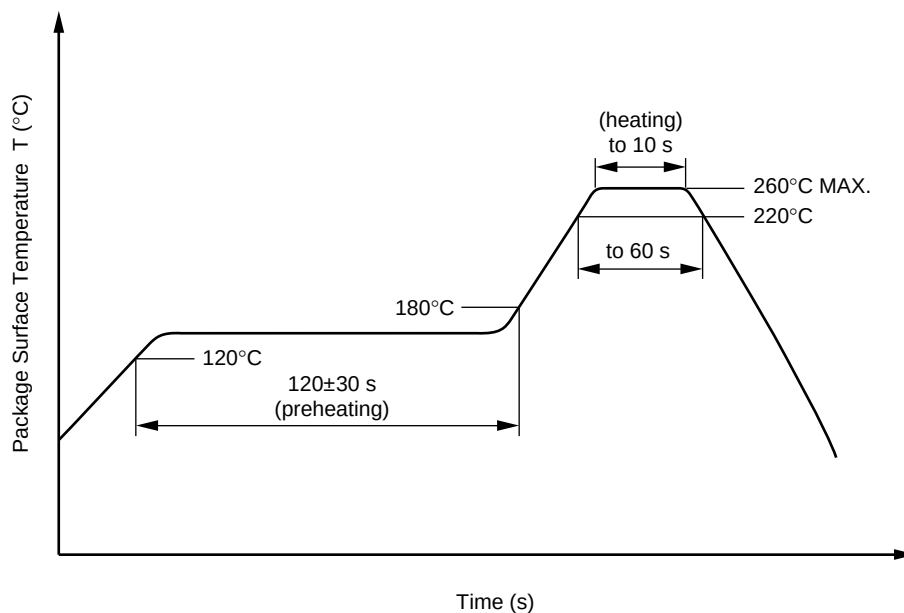
Packing: 2 000 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)

Part Number	Lead Bending	A	B	C	D
PS9309L	lead bending type (Gull-wing) for surface mount	9.2	1.27	0.8	2.2
PS9309L2	lead bending type (Gull-wing) for long creepage distance (surface mount)	10.2	1.27	0.8	2.2

<R> NOTES ON HANDLING (UNIT: mm)**1. Recommended soldering conditions****(1) Infrared reflow soldering**

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120 ± 30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow**(2) Wave soldering**

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

- Peak Temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(4) Cautions

- Fluxes Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

USAGE CAUTIONS

1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than 0.1 μ F is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Pin 2 (which is an NC^{*1} pin) can either be connected directly to the GND pin on the LED side or left open. Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.

Note: *1. NC: Non-Connection (No Connection).

4. Avoid storage at a high temperature and high humidity.

<R>

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/110/21	
Dielectric strength			
maximum operating isolation voltage	U_{IORM}	1 130	V_{peak}
Test voltage (partial discharge test, procedure a for type test and random test)	U_{pr}	1 808	V_{peak}
$U_{pr} = 1.6 \times U_{IORM.}, P_d < 5 \text{ pC}$			
Test voltage (partial discharge test, procedure b for all devices)	U_{pr}	2 119	V_{peak}
$U_{pr} = 1.875 \times U_{IORM.}, P_d < 5 \text{ pC}$			
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +125	°C
Operating temperature range	T_A	-40 to +110	°C
Isolation resistance, minimum value			
$V_{IO} = 500 \text{ V dc at } T_A = 25^\circ\text{C}$	Ris MIN.	10^{12}	Ω
$V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100^\circ\text{C}$	Ris MIN.	10^{11}	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Package temperature	T_{si}	175	°C
Current (input current I_F , $P_{si} = 0$)	I_{si}	400	mA
Power (output or total power dissipation)	P_{si}	700	mW
Isolation resistance			
$V_{IO} = 500 \text{ V dc at } T_A = T_{si}$	Ris MIN.	10^9	Ω

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

Revision History	PS9309L, PS9309L2 Data Sheet
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Rev.	Date	Description	
		Page	Summary
0.01	Feb 14, 2012	–	First edition issued
1.00	Mar 28, 2014	p.1	Modification of FEATURES
		p.4	Modification of ORDERING INFORMATION
		p.8 to 9	Addition of TYPICAL CHARACTERISTICS
		p.10 to 11	Modification of TAPING SPECIFICATIONS
		p.13	Addition of NOTES ON HANDLING
		p.15	Modification of SPECIFICATION OF VDE MARKS LICENCE DOCUMENT

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SALES OFFICES

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California Eastern Laboratories, Inc.
4590 Patrick Henry Drive, Santa Clara, California 95054, U.S.A.
Tel: +1-408-919-2500, Fax: +1-408-988-0279

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
Room 1709, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100191, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, P. R. China 200333
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2265-6688, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
12F., 234 Teheran-ro, Gangnam-Ku, Seoul, 135-920, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141